Ĺ	Hits	Search Text	DB	Time stamp
Number	11200			_
15	4	(("6329298") or ("6099598") or	USPAT	2003/06/10
1.0	5	("4985113") or ("5670421")).PN.	tic D a m	11:38
16	5	(("6329298") or ("6099598") or ("4985113") or ("5670421") or	USPAT	2003/06/10 13:56
		("6350687")).PN.		13.30
_	2		USPAT	2003/06/10
	_	(,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,		11:25
_	581	438/687	USPAT;	2002/02/14
			EPO; JPO;	09:10
		400/000 3 / 11	DERWENT	0000/00/05
_	0	438/687 and (anti-corrosion adj treat\$5)	USPAT;	2002/02/05
			EPO; JPO; DERWENT	12:48
_	0	438/687 and ((anti-corrosion or (corros\$5	USPAT;	2002/10/21
		adj inhibit\$5)) adj treat\$5)	EPO; JPO;	13:59
			DERWENT	10,000
_	0	438/687 and ((corros\$5 adj inhibit\$5) adj	USPAT;	2002/02/14
		treat\$5)	EPO; JPO;	09:17
			DERWENT	
_	2		USPAT;	2002/02/05
		and semiconductor	EPO; JPO;	12:50
	16	(anti-corregion add treates) and	DERWENT USPAT;	2002/02/05
_	10	(anti-corrosion adj treat\$5) and semiconductor	EPO; JPO;	12:50
		- Same Solida Col	DERWENT	
_	18	(((anti-corrosion or (corros\$5 adj	USPAT;	2003/06/04
		inhibit\$5)) adj treat\$5)) and	EPO; JPO;	08:57
		semiconductor	DERWENT	
-	186	((corros\$5 adj inhibit\$5) adj treat\$5)	USPAT;	2002/02/05
			EPO; JPO;	12:56
	222		DERWENT	2002/08/06
_	223	anti-corrosion adj treat\$5	USPAT; EPO; JPO;	14:53
			DERWENT	14.00
	407	((anti-corrosion or (corros\$5 adj	USPAT;	2002/02/05
		inhibit\$5)) adj treat\$5)	EPO; JPO;	13:12
			DERWENT	
-	3	'	USPAT	2002/02/05
	F 0.1.0	("6323131")).PN.	HCDAM.	13:43
_	5218	anti-corrosive	USPAT; EPO; JPO;	2002/10/21
			DERWENT	15.45
_	946	anti-corrosive and copper	USPAT;	2002/02/14
		· · · · · · · · · · · · · · · · · · ·	EPO; JPO;	09:18
			DERWENT	
-	450808	copper	USPAT;	2002/10/21
			EPO; JPO;	13:57
_	046	gonner and anti servesive	DERWENT	2002/02/14
_	946	copper and anti-corrosive	USPAT; EPO; JPO;	2002/02/14
			DERWENT	05.20
_	0	(copper and anti-corrosive) and	USPAT;	2002/02/14
		(hetero-cyclic)	EPO; JPO;	09:19
		_	DERWENT	
-	2	1 ' ++	USPAT;	2002/02/14
		adj cyclic)	EPO; JPO;	09:19
_		//gappar and anti-gappagival and /hatava	DERWENT	2002/02/14
-	0	((copper and anti-corrosive) and (hetero adj cyclic)) and (indazole)	USPAT; EPO; JPO;	2002/02/14 09:29
		adj cyclic// and (indazole/	DERWENT	
_	4	(copper and anti-corrosive) and	USPAT;	2002/02/14
	_	(indazole)	EPO; JPO;	09:24
			DERWENT	
-	0	((copper and anti-corrosive) and	USPAT;	2002/02/14
		(indazole)) and semiconductor	EPO; JPO;	09:29
	2175	genner and ((anti-genresive) or (anti-set	DERWENT USPAT;	2002/02/14
-	21/5	copper and ((anti-corrosive) or (anti adj corrosion))	EPO; JPO;	10:28
		0011001011//	DERWENT	
	l			

ſ	-	0	((copper and ((anti-corrosive) or (anti	USPAT;	2002/02/14
ı			adj corrosion))) and (indazole)) and	EPO; JPO;	09:30
ı			semiconductor	DERWENT	
ı	-	12	(copper and ((anti-corrosive) or (anti	USPAT;	2002/02/14
١			adj corrosion))) and (indazole)	EPO; JPO;	10:29
١			, , , , , , , , , , , , , , , , , , , ,	DERWENT	
ı	_	171	(copper and ((anti-corrosive) or (anti	USPAT;	2002/02/19
ł			adj corrosion))) and semiconductor	EPO; JPO;	12:34
ł			day correston, , , and semiconductor	DERWENT	12.91
		0	((copper and ((anti-corrosive) or (anti	USPAT;	2002/02/14
	-	0	adj corrosion))) and semiconductor) and	EPO; JPO;	10:02
ļ					10:02
1		50400	(indazole)	DERWENT	2002/02/14
1	-	52420	copper and ((anticorros\$3) or (corros\$3))	USPAT;	,
1				EPO; JPO;	10:29
1			1, 1, 1, 1, 1, 1, 1, 1, 1, 1, 1, 1, 1, 1	DERWENT	0000/00/114
1	-	163	(copper and ((anticorros\$3) or	USPAT;	2002/02/14
١			(corros\$3))) and (indazole)	EPO; JPO;	10:29
١				DERWENT	
١	-	20	((copper and ((anticorros\$3) or	USPAT;	2002/02/14
			(corros\$3))) and (indazole)) and	EPO; JPO;	10:32
			semiconductor	DERWENT	
1	- !	16		USPAT;	2002/02/14
			(corros\$3))) and (indazole)) and	EPO; JPO;	14:37
	l		(interconnect\$3 or wir\$4 or (sheet adj	DERWENT	
			metal))		
1	_	3		USPAT	2002/02/14
			("5455202")).PN.		14:38
1	_	172	(copper and ((anti-corrosive) or (anti	USPAT;	2002/02/19
1			adj corrosion))) and semiconductor	EPO; JPO;	12:39
1			aug correspond, , , una semirochiadoca	DERWENT	
1	_	3	((copper and ((anti-corrosive) or (anti	USPAT;	2002/02/19
1		3	adj corrosion))) and semiconductor) and	EPO; JPO;	12:38
ı			(SiON or (silicon adj oxygen adj	DERWENT	12.30
١			nitrogen))	DEKWENI	
1		2176		USPAT;	2002/02/19
1	-	21/6			12:38
1			adj corrosion)))	EPO; JPO;	12:30
1		2		DERWENT	2002/02/10
1	-	3	(((copper and ((anti-corrosive) or (anti	USPAT;	2002/02/19
1			adj corrosion)))) and (SiON or (silicon	EPO; JPO;	12:39
			adj oxygen adj nitrogen))) and	DERWENT	
1	İ		semiconductor	Henam.	2002/02/10
1	-	23		USPAT;	2002/02/19
1			adj corrosion)))) and (SiON or (silicon	EPO; JPO;	12:39
			adj oxygen adj nitrogen))	DERWENT	1 2000 /20 /25
1	-	609	(438/687).CCLS.	USPAT;	2002/08/06
				US-PGPUB;	14:53
1	ļ			EPO; JPO;	
1				DERWENT;	
				IBM_TDB	
1	-	484110	copper	USPAT;	2002/08/06
١				US-PGPUB;	14:53
				EPO; JPO;	
				DERWENT;	
Ī				IBM_TDB	
1	_	836479	copper or ("cu")	USPĀT;	2002/08/06
				US-PGPUB;	14:54
	j			EPO; JPO;	
				DERWENT;	
1	į			IBM_TDB	
	- 1	235539	(copper or ("cu")) and treat\$5	USPĀT;	2002/08/06
I			· · · · · · · · · · · · · · · · ·	US-PGPUB;	14:56
1	ļ			EPO; JPO;	
١	İ			DERWENT;	
1				IBM TDB	
1	_	4708	((copper or ("cu")) and treat\$5) and	USPAT;	2002/08/06
1			(corros\$5 adj (inhibit\$5 or treat\$5))	US-PGPUB;	14:58
				EPO; JPO;	
1				DERWENT;	
1				IBM TDB	
1	ı				1

		,		
_	255	(((copper or ("cu")) and treat\$5) and (corros\$5 adj (inhibit\$5 or treat\$5))) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/06 14:58
			IBM_TDB	
-	38	<pre>((((copper or ("cu")) and treat\$5) and (corros\$5 adj (inhibit\$5 or treat\$5))) and semiconductor) and (anti-corros\$5 or (anti adj corros\$5))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/06 14:59
-	1	("6274478").PN.	IBM_TDB USPAT	2002/08/06
_	0	((anti-corrosive or (anti adj corrosive))	USPAT;	2002/10/21
	: :	adj treat\$5) same ((copper-diffus\$4 or (copper adj diffus\$4)) adj (stop\$5 or barrier) adj (layer or film))	US-PGPUB; EPO; JPO; DERWENT; IBM TDB	13:50
_	129	(anti-corrosive or (anti adj corrosive)) adj treat\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 14:55
-	7	((anti-corrosive or (anti adj corrosive)) adj treat\$5) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 14:01
-	483451	copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 13:58
-	121	<pre>copper and ((anti-corrosion or (anti adj corros\$4) or (corros\$5 adj inhibit\$5)) adj treat\$5)</pre>	USPAT; EPO; JPO; DERWENT	2002/10/21 14:01
_	139		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21
-	24	<pre>(copper and ((anti-corrosion or (anti adj corros\$4) or (corros\$5 adj inhibit\$5)) adj treat\$5)) and semiconductor</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 14:54
-	0	<pre>(semiconductor adj substrate) same ((anti-corrosive or (anti adj corrosive)) adj treat\$5)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 14:56
-	1	("6350687").PN.	USPAT	2002/10/22 14:23
-	0	("jp11003892").PN.	JPO	2002/10/22 13:07
-	3	(("6350687") or ("5670421") or ("6323131")).PN.	USPAT	2002/10/22 14:24
-	57		USPAT; EPO; JPO; DERWENT	2003/06/04 09:01
-	79		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/04 10:21
-	1	(((anticorros\$5 or anti-corros\$5 or (anti adj corros\$5)) or (corros\$5 adj inhibit\$5)) adj (treat\$5)) and ((cu or copper) adj (diffus\$6 adj (barrier or stop\$6))) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/04 10:20

	1	(((anticorros\$5 or anti-corros\$5 or (anti	USPAT;	2003/06/04
		adj corros\$5)) or (corros\$5 adj	US-PGPUB;	10:20
		inhibit\$5)) adj (treat\$5)) and ((cu or	EPO; JPO;	
	İ	copper) adj (diffus\$6 adj (barrier or	DERWENT;	1
		stop\$6)))	IBM TDB	
-	37	((((anticorros\$5 or anti-corros\$5 or	USPĀT;	2003/06/04
		(anti adj corros\$5)) or (corros\$5 adj	US-PGPUB;	10:21
		inhibit\$5)) adj (treat\$5)) and	EPO; JPO;	
	•	semiconductor) and (cu or copper)	DERWENT;	
1			IBM TDB	
-	55	((((anticorros\$5 or anti-corros\$5 or	USPAT;	2003/06/04
		(anti adj corros\$5)) or (corros\$5 adj	US-PGPUB;	10:21
		inhibit\$5)) adj (treat\$5)) and	EPO; JPO;	
		semiconductor) and (cu or copper)	DERWENT;	l
			IBM TDB	